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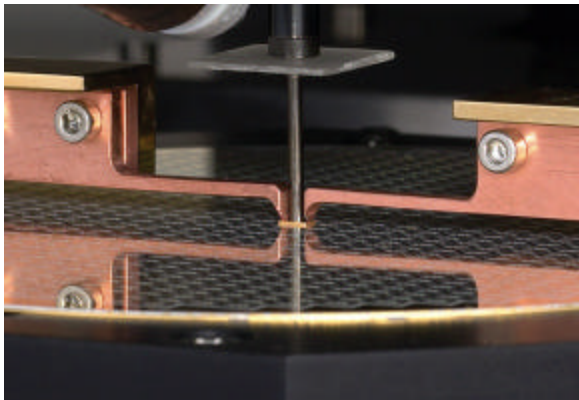
New SSEC System Achieves High Volume Wafer-level Sealing

Horsham, PA—Applying its parallel seam sealing technology to the emerging MEMS market, Solid State Equipment Corporation announces a completely automatic, high volume, wafer-level sealer. This system provides placement accuracy better than $\pm 0.002"$ ϕ and yields of better than 99%, ensured by automatic lid placement and lid placement inspection. Special illumination and a programmable, heated stage allow sealing directly to metalized wafer surfaces using lids with a solder pre-form.

SSEC has refined parallel seam sealing as a production tool, with DSP power control of pulse parameters and precision, closed-loop controlled motion. An internal network integrates all control functions, including the Window[®] operator interface.

Solid State Equipment Corporation manufactures a full line of parallel seam sealers and one-shot welders at its headquarters in suburban Philadelphia. These systems are complemented with heated/cooled shelf ovens for internal device atmosphere control and environmental systems that incorporate programmable control of gas mixing. SSEC has been developing and manufacturing technology solutions for semiconductor processing for over 40 years.

SSEC maintains sales and service officers worldwide, and customer support and process development centers in Horsham, Pennsylvania, Regensburg, Germany, Newcastle, England, Taiwan, R.O.C., Shanghai, P.R.C., and Woodlands, Singapore. For further information, contact Rich Richardson at SSEC, 215-328-0700, FAX 267-965-2841, or info@ssecusa.com, or visit www.ssecusa.com.



SSEC's parallel seam sealing technology achieves high volume, precise wafer-level sealing for MEMS applications with yields better than $\pm 0.002"$ ϕ .

